DATA SHEET

TDA8771
Triple 8-bit video digital-to-analog converter

Product specification
Supersedes data of April 1994
File under Integrated Circuits, IC02

1995 Mar 09

PHILIPS

Triple 8-bit video digital-to-analog converter

TDA8771

FEATURES

- 8-bit resolution
- Sampling rate up to 35 MHz
- Internal reference voltage regulator
- No deglitching circuit required
- Large output voltage range
- 1 kΩ output load
- Power dissipation only 200 mW
- Single 5 V power supply
- 44-pin QFP package.

APPLICATIONS

- General purpose high-speed digital-to-analog conversion
- Digital TV
- Graphic display
- Desktop video processing.

GENERAL DESCRIPTION

The TDA8771 is a triple 8-bit video digital-to-analog converter (DAC). It converts the digital input signals into analog voltage outputs at a maximum conversion rate of 35 MHz.

The DACs are based on resistor-string architecture with integrated output buffers. The output voltage range is determined by a built-in reference source.

The device is fabricated in a 5 V, CMOS process that ensures high functionality with low power dissipation.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{DDA}	analog supply voltage		4.5	5.0	5.5	V
V_{DDD}	digital supply voltage		4.5	5.0	5.5	V
I_{DDA}	analog supply current	R_L = 1 kΩ; note 1	10	33	45	mA
I_{DDD}	digital supply current	f_{clk} = 35 MHz	–	7	20	mA
INL	integral non-linearity	f_{clk} = 35 MHz; ramp input	–	±0.5	±1	LSB
DNL	differential non-linearity	f_{clk} = 35 MHz; ramp input	–	±0.25	±0.5	LSB
$f_{clk(max)}$	maximum clock frequency		35	–	–	MHz
P_{tot}	total power dissipation	R_L = 1 kΩ; f_{clk} = 35 MHz; note 1	45	200	360	mW

Note

1. Minimum and maximum data of current and power consumption are measured in worse case conditions: for minimum data, all digital inputs are at logic level 0 while for maximum data, all digital inputs are at logic level 1.

ORDERING INFORMATION

TYPE NUMBER	PACKAGE			
	PINS	PIN POSITION	MATERIAL	CODE
TDA8771H	44	QFP	plastic	SOT307-2

BLOCK DIAGRAM

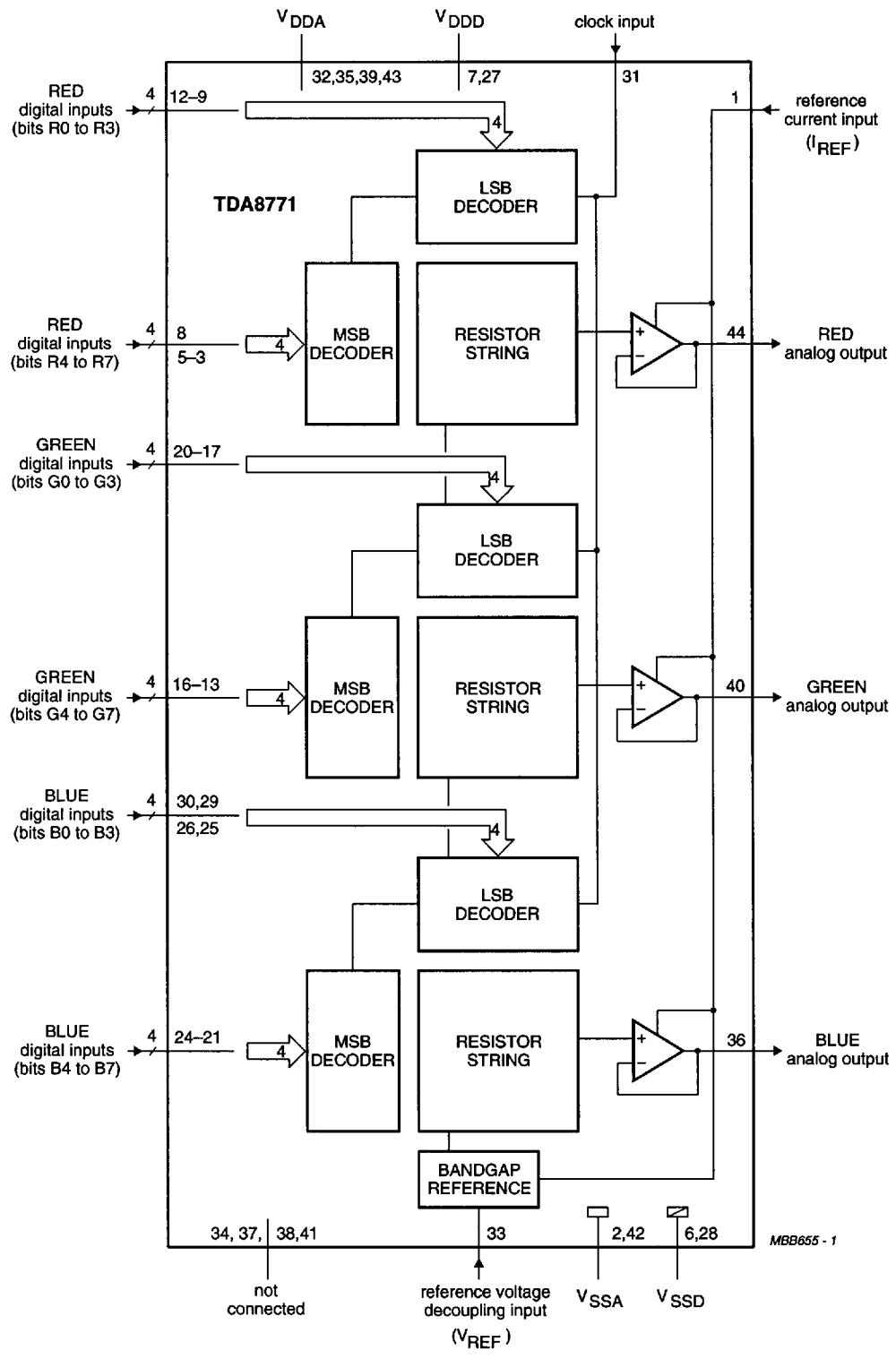


Fig.1 Block diagram.

PINNING

SYMBOL	PIN	DESCRIPTION
I_{REF}	1	reference current input for output buffers
V_{SSA1}	2	analog supply ground 1
R7	3	RED digital input data; bit 7 (MSB)
R6	4	RED digital input data; bit 6
R5	5	RED digital input data; bit 5
V_{SSD1}	6	digital supply ground 1
V_{DDD1}	7	digital supply voltage 1
R4	8	RED digital input data; bit 4
R3	9	RED digital input data; bit 3
R2	10	RED digital input data; bit 2
R1	11	RED digital input data; bit 1
R0	12	RED digital input data; bit 0 (LSB)
G7	13	GREEN digital input data; bit 7 (MSB)
G6	14	GREEN digital input data; bit 6
G5	15	GREEN digital input data; bit 5
G4	16	GREEN digital input data; bit 4
G3	17	GREEN digital input data; bit 3
G2	18	GREEN digital input data; bit 2
G1	19	GREEN digital input data; bit 1
G0	20	GREEN digital input data; bit 0 (LSB)
B7	21	BLUE digital input data; bit 7 (MSB)
B6	22	BLUE digital input data; bit 6
B5	23	BLUE digital input data; bit 5
B4	24	BLUE digital input data; bit 4
B3	25	BLUE digital input data; bit 3
B2	26	BLUE digital input data; bit 2
V_{DDD2}	27	digital supply voltage 2
V_{SSD2}	28	digital supply ground 2
B1	29	BLUE digital input data; bit 1
B0	30	BLUE digital input data; bit 0 (LSB)
CLK	31	clock input
V_{DDA1}	32	analog supply voltage 1
V_{REF}	33	decoupling input for reference voltage
n.c.	34	not connected
V_{DDA2}	35	analog supply voltage 2
OUTB	36	BLUE analog output
n.c.	37	not connected
n.c.	38	not connected
V_{DDA3}	39	analog supply voltage 3
OUTG	40	GREEN analog output

SYMBOL	PIN	DESCRIPTION
n.c.	41	not connected
V_{SSA2}	42	analog supply ground 2
V_{DDA4}	43	analog supply voltage 4
OUTR	44	RED analog output

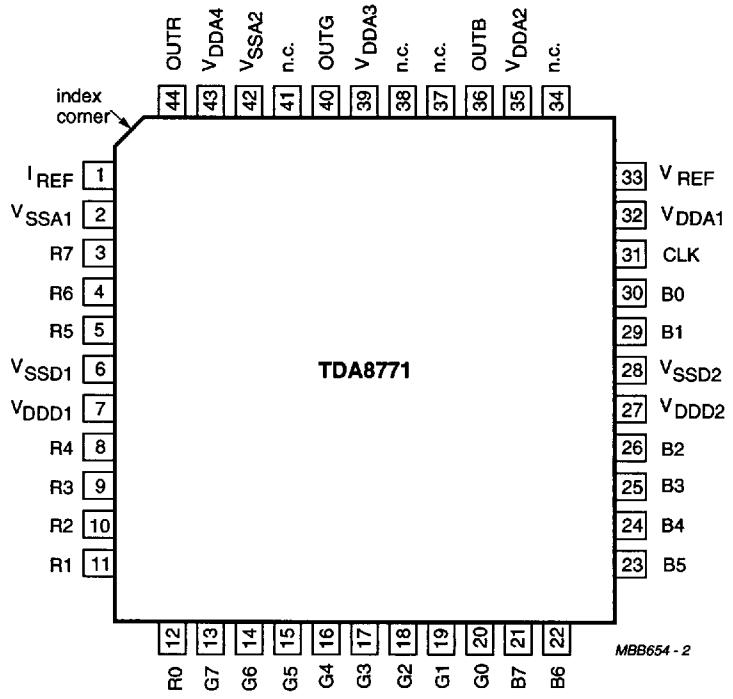


Fig.2 Pin configuration.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V_{DDA}	analog supply voltage	−0.5	+6.5	V
V_{DDD}	digital supply voltage	−0.5	+6.5	V
ΔV_{DD}	supply voltage difference between V_{DDA} and V_{DDD}	−1.0	+1.0	V
T_{stg}	storage temperature	−55	+150	°C
T_{amb}	operating ambient temperature	0	+70	°C
T_j	junction temperature	−	+125	°C

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
$R_{th\ j\text{-}a}$	thermal resistance from junction to ambient in free air	75	K/W

HANDLING

Inputs and outputs are protected against electrostatic discharges in normal handling. However, to be totally safe, it is desirable to take normal precautions appropriate to handling integrated circuits.

CHARACTERISTICS

$V_{DDA} = V_{DDD} = 4.5$ to 5.5 V; V_{SSA} and V_{SSD} shorted together; $V_{DDA} - V_{DDD} = -0.5$ to +0.5 V; $T_{amb} = 0$ to +70 °C; typical values measured at $V_{DDA} = V_{DDD} = 5$ V and $T_{amb} = 25$ °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supply						
V_{DDA}	analog supply voltage		4.5	5.0	5.5	V
V_{DDD}	digital supply voltage		4.5	5.0	5.5	V
I_{DDA}	analog supply current	R_L = 1 kΩ; note 1	10	33	45	mA
I_{DDD}	digital supply current	f_{clk} = 35 MHz	–	7	20	mA
Inputs						
CLOCK INPUT (PIN 31)						
V_{IL}	LOW level input voltage		0	–	1.2	V
V_{IH}	HIGH level input voltage		2.0	–	V_{DDD}	V
R, G, B DIGITAL INPUTS (PINS 12 TO 8, 5 TO 3, 20 TO 13, 30, 29 AND 26 TO 21)						
V_{IL}	LOW level input voltage		0	–	1.2	V
V_{IH}	HIGH level input voltage		2.0	–	V_{DDD}	V
I_{REF} REFERENCE CURRENT INPUT FOR OUTPUT BUFFERS (PIN 1)						
I_I	input current		–	0.6	0.7	mA
Timing; see Fig.3						
$f_{clk(max)}$	maximum clock frequency		35	–	–	MHz
t_{CPH}	clock pulse width HIGH		8	–	–	ns
t_{CPL}	clock pulse width LOW		8	–	–	ns
t_r	clock rise time		–	–	5	ns
t_f	clock fall time		–	–	6	ns
$t_{SU;DAT}$	input data set-up time		4	–	–	ns
$t_{HD;DAT}$	input data hold time		4	–	–	ns
Voltage reference (pin 33, referenced to V_{SSA})						
V_{REF}	output reference voltage		1.180	1.242	1.305	V
Outputs						
OUTB, OUTR, OUTG ANALOG OUTPUTS (PINS 36, 44 AND 40, REFERENCED TO V_{SSA}) FOR 1 kΩ LOAD; see Table 1						
FSR	full-scale output voltage range		2.80	2.95	3.10	V
V_{os}	offset of analog voltage output		–	0.25	–	V
V_{Omax}	maximum output voltage	data inputs = logic 1; note 2	2.95	3.20	3.45	V
V_{Omin}	minimum output voltage	data inputs = logic 0; note 2	0.05	0.25	0.45	V
THD	total harmonic distortion	f_i = 4.43 MHz; f_{clk} = 35 MHz	–	–44	–	dB
Z_L	output load impedance		0.9	1.0	1.1	kΩ

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Transfer function (f_{clk} = 35 MHz)						
INL	integral non-linearity	ramp input	–	0.5	±1	LSB
DNL	differential non-linearity	ramp input	–	0.25	±0.5	LSB
α_{CT}	crosstalk DAC to DAC		−50	–	–	dB
	DAC to DAC matching		–	1.0	2.0	%
Switching characteristics (for 1 kΩ output load); see Fig.4						
t_d	input to 50% output delay time	full-scale change	–	12	–	ns
t_{s1}	settling time	10% to 90% of full-scale change	–	15	–	ns
t_{s2}	settling time	to ±1 LSB	–	50	–	ns
Output transients (glitches)						
V_g	area for 1 LSB change		–	1	–	LSB·ns

Notes

1. Minimum and maximum data of current and power consumption are measured in worse case conditions: for minimum data, all digital inputs are at logic level 0 while for maximum data, all digital inputs are at logic level 1.
2. V_O is directly proportional to V_{REF}.

Table 1 Input coding and DAC output voltages (typical values)

BINARY INPUT DATA (SYNC = BLANK = 0)	CODE	DAC OUTPUT VOLTAGES (V) OUTB, OUTR, OUTG R_L = 1 kΩ
0000 0000	0	0.262
0000 0001	1	0.273
....	.	.
1000 0000	128	1.731
....	.	.
1111 1110	254	3.188
1111 1111	255	3.200

TIMING

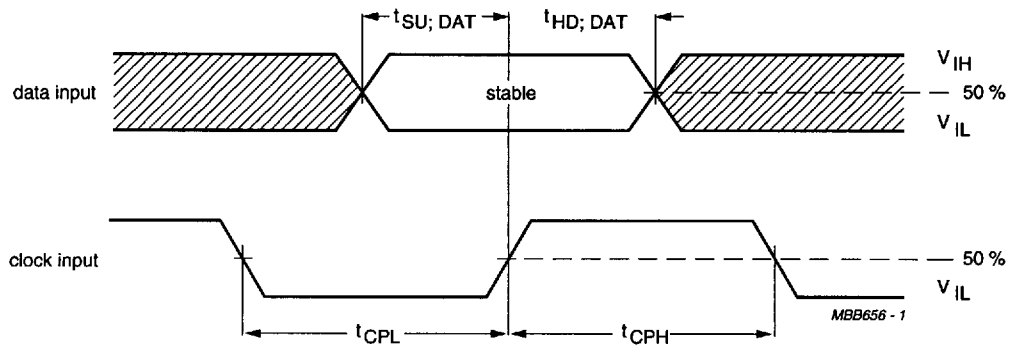


Fig.3 Input timing.

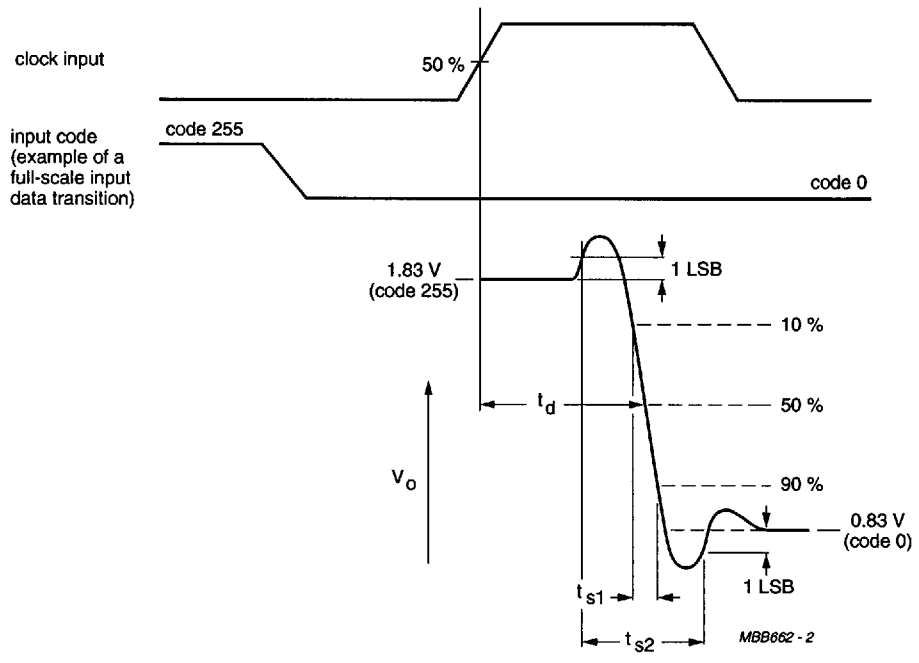
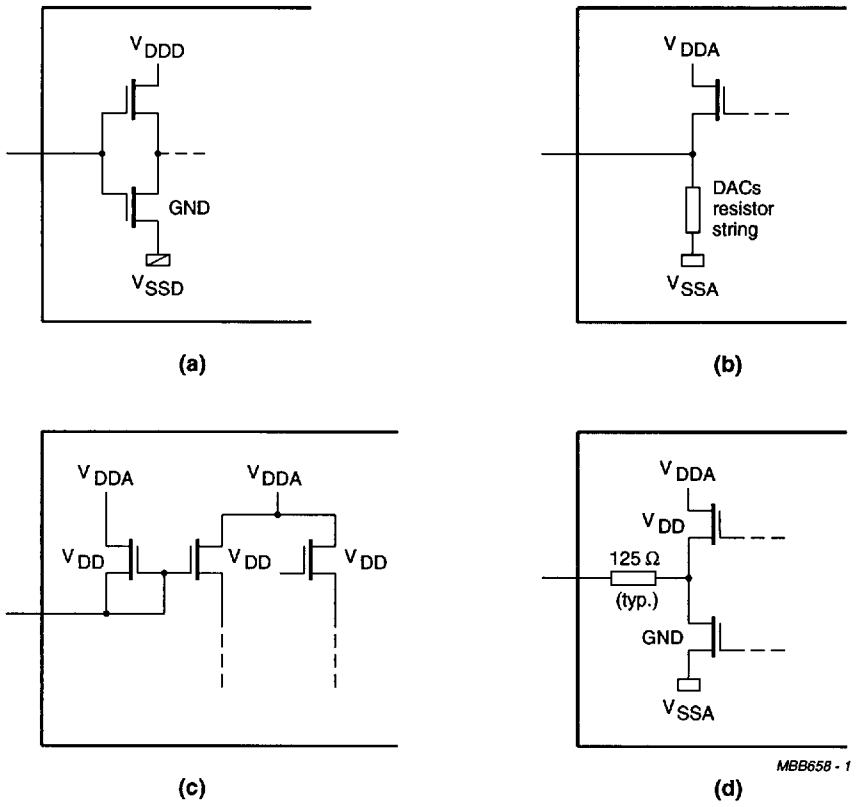


Fig.4 Switching timing.

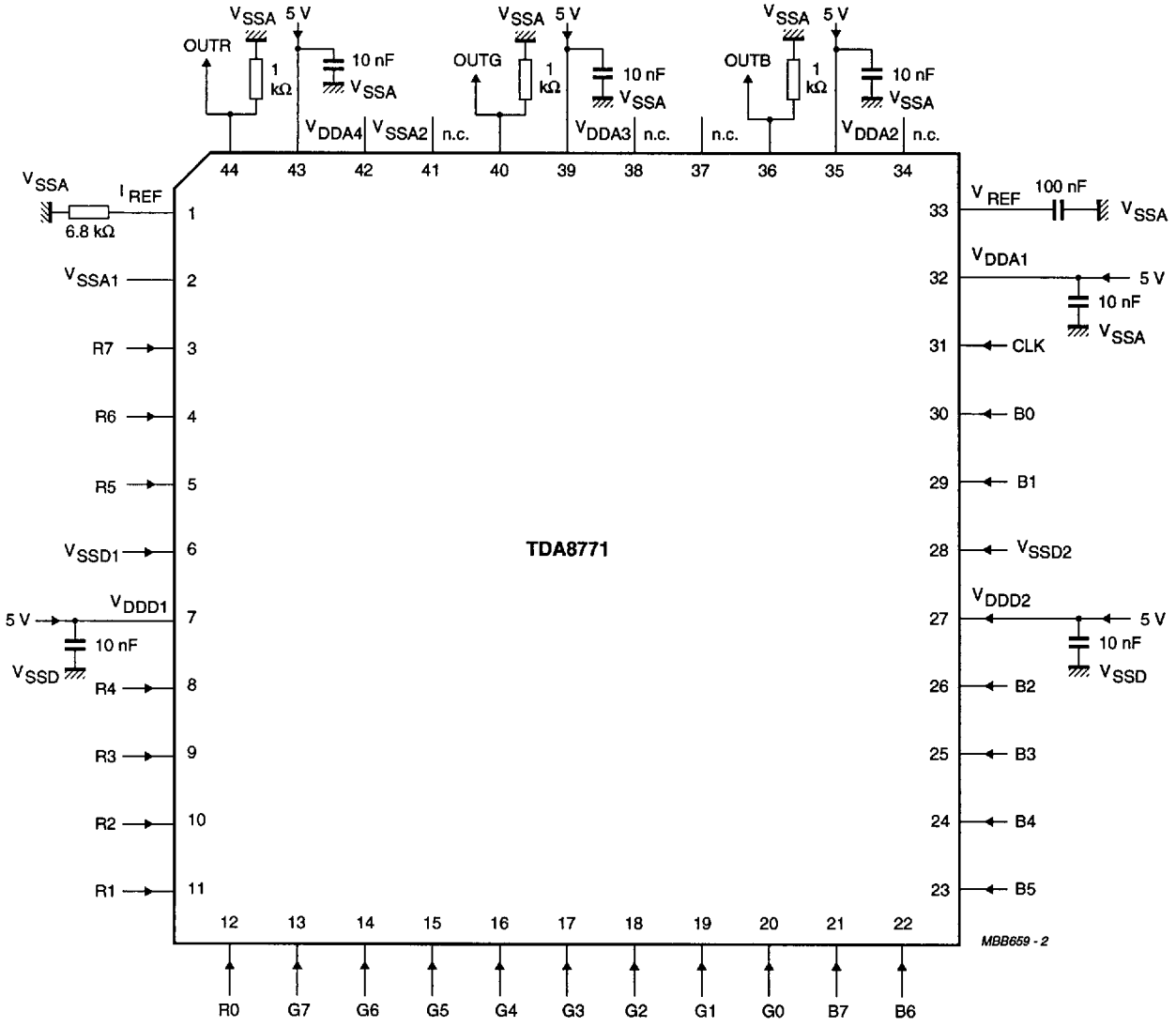
INTERNAL CIRCUITRY



(a) Digital inputs; pins 3 to 5, 8 to 26 and 29 to 31.
(b) V_{REF}; pin 33.
(c) I_{REF}; pin 1.
(d) OUTR, G, B; pins 44, 40 and 36.

Fig.5 Internal circuitry.

APPLICATION INFORMATION



Analog and digital supplies should be separated and decoupled.
Supplies are not connected internally.
All ground pins must be connected. One ground plane is preferred although it depends on application.
See Figs 7 and 9 for example of anti-aliasing filter.

Fig.6 Application diagram.

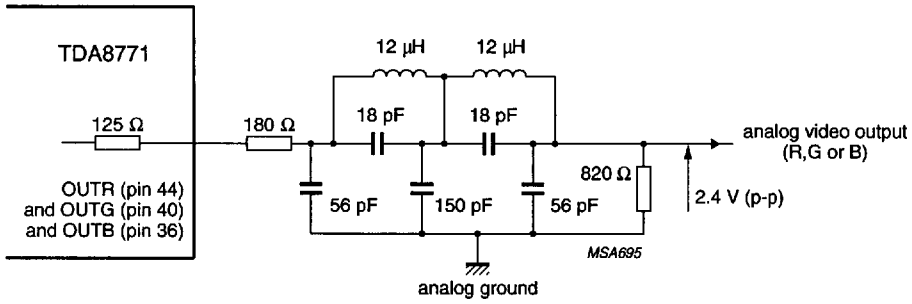


Fig.7 Example of anti-aliasing filter for 2.4 V output swing.

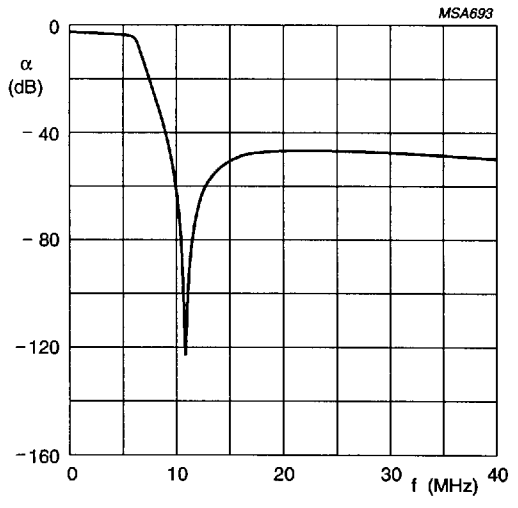


Fig.8 Frequency response for filter shown in Fig.7.

Characteristics of Fig.8

- Order 5; adapted CHEBYSHEV
- Ripple $\rho \geq 0.7$ dB
- f at −3 dB = 6.2 MHz
- f_{NOTCH} = 10.8 MHz.

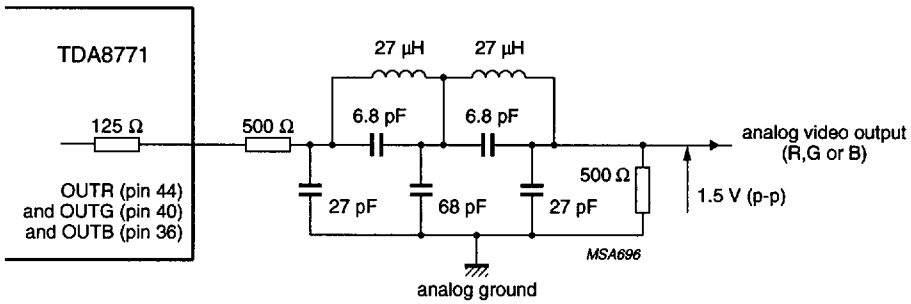


Fig.9 Example of anti-aliasing filter for 1.5 V output swing.

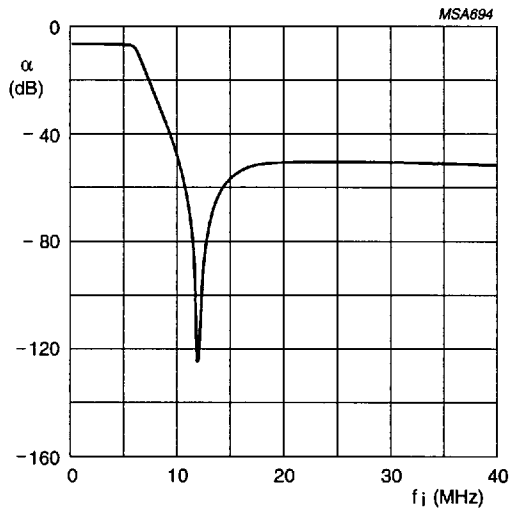


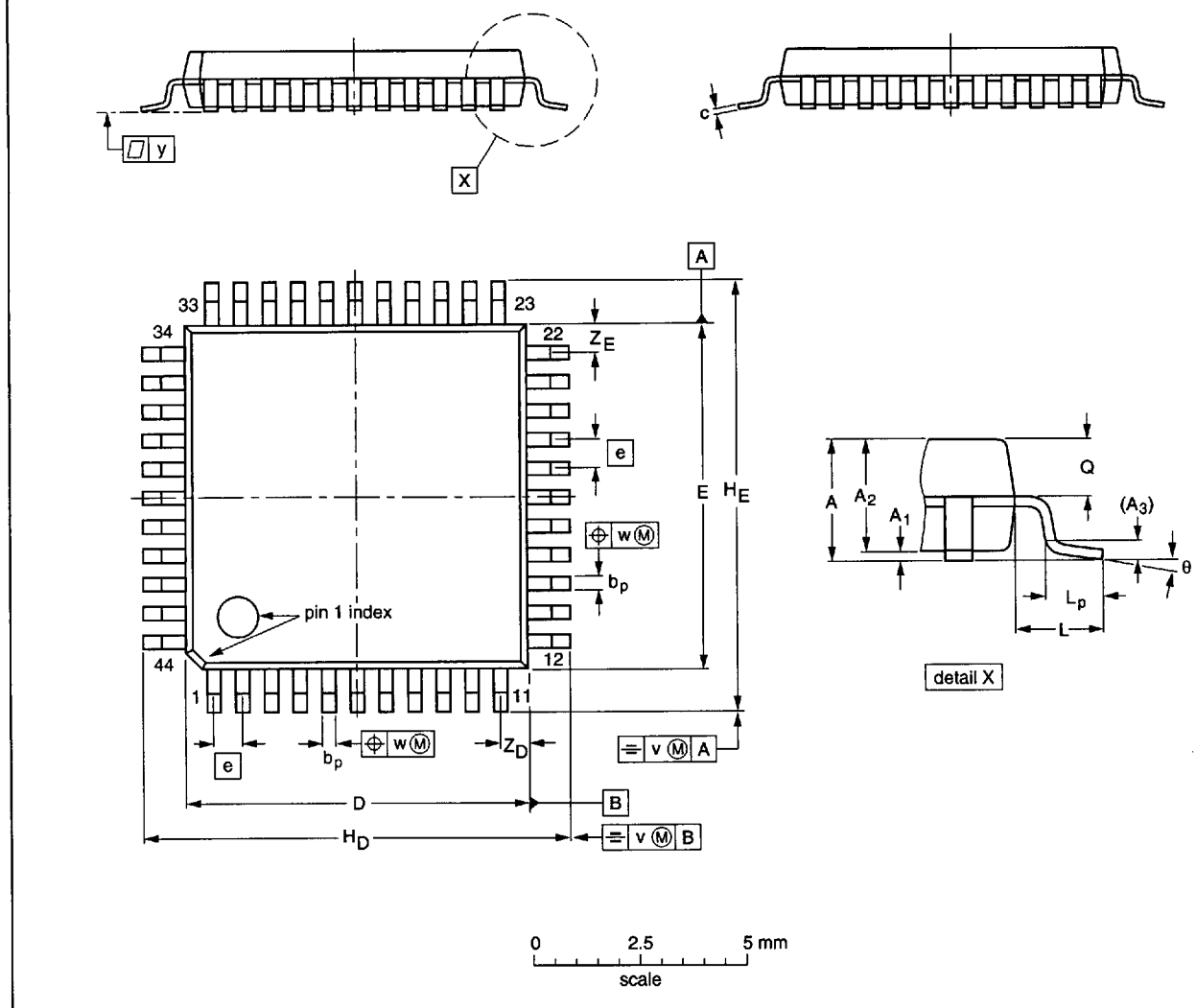
Fig.10 Frequency response for filter shown in Fig.9.

Characteristics of Fig.10

- Order 5; adapted CHEBYSHEV
- Ripple $\rho \geq 0.25$ dB
- f at −3 dB = 5.6 MHz
- f_{NOTCH} = 11.7 MHz.

PACKAGE OUTLINE

QFP44: plastic quad flat package; 44 leads (lead length 1.3 mm); body 10 x 10 x 1.75 mm **SOT307-2**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_D	H_E	L	L_p	Q	v	w	y	$Z_D^{(1)}$	$Z_E^{(1)}$	θ
mm	2.10	0.25 0.05	1.85 1.65	0.25	0.40 0.20	0.25 0.14	10.1 9.9	10.1 9.9	0.8	12.9 12.3	12.9 12.3	1.3	0.95 0.55	0.85 0.75	0.15	0.15	0.1	1.2 0.8	1.2 0.8	10° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT307-2						~~92-11-17~~ 95-02-04

SOLDERING

Plastic quad flat packages

BY WAVE

During placement and before soldering, the component must be fixed with a droplet of adhesive. After curing the adhesive, the component can be soldered. The adhesive can be applied by screen printing, pin transfer or syringe dispensing.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder bath is 10 s, if allowed to cool to less than 150 °C within 6 s. Typical dwell time is 4 s at 250 °C.

A modified wave soldering technique is recommended using two solder waves (dual-wave), in which a turbulent wave with high upward pressure is followed by a smooth laminar wave. Using a mildly-activated flux eliminates the need for removal of corrosive residues in most applications.

BY SOLDER PASTE REFLOW

Reflow soldering requires the solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the substrate by screen printing, stencilling or pressure-syringe dispensing before device placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt, infrared, and vapour-phase reflow. Dwell times vary between 50 and 300 s according to method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 min at 45 °C.

REPAIRING SOLDERED JOINTS (BY HAND-HELD SOLDERING IRON OR PULSE-HEATED SOLDER TOOL)

Fix the component by first soldering two, diagonally opposite, end pins. Apply the heating tool to the flat part of the pin only. Contact time must be limited to 10 s at up to 300 °C. When using proper tools, all other pins can be soldered in one operation within 2 to 5 s at between 270 and 320 °C. (Pulse-heated soldering is not recommended for SO packages.)

For pulse-heated solder tool (resistance) soldering of VSO packages, solder is applied to the substrate by dipping or by an extra thick tin/lead plating before package placement.

DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

LIFE SUPPORT APPLICATIONS

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